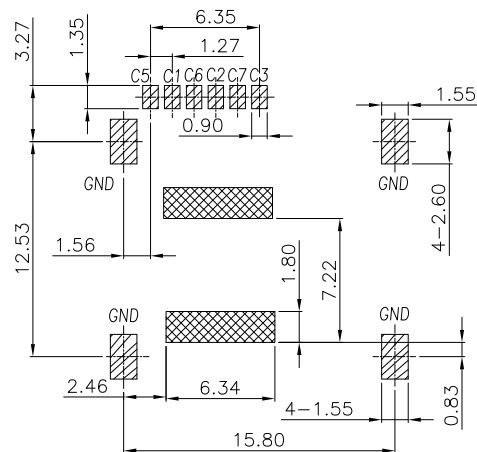
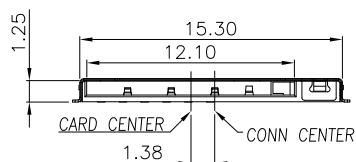
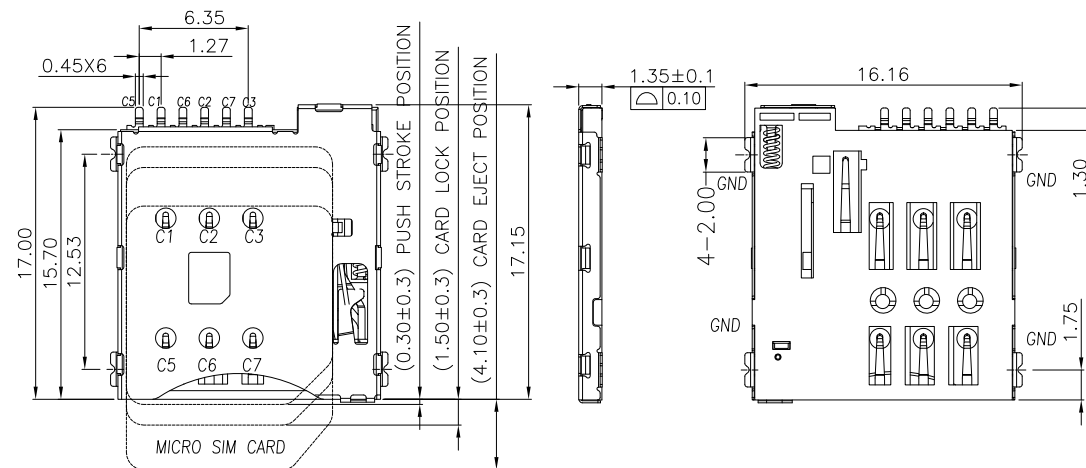


FORBIDDEN AREA

SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ± 0.05

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

1) MATERIAL:

- 1.1 HOUSING: LCP, UL94-V0, COLOR: BLACK
- 1.2 CONTACT: C5210R-H
- 1.3 SHELL: SUS304-H

2) FINISH:

- 2.1 TERMINAL: 30 μ Min. NICKEL PLATED OVERALL
- 2.2 CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS;

3) ELECTRICAL CHARACTERISTICS

RATING CURRENT : 0.5A MAX.
CONTACT RESISTANCE : 50 m Ω MAX
DIELECTRIC WITHSTANDING : 500V AC MIN.
INSULATION RESISTANCE: 1000 M Ω MIN.

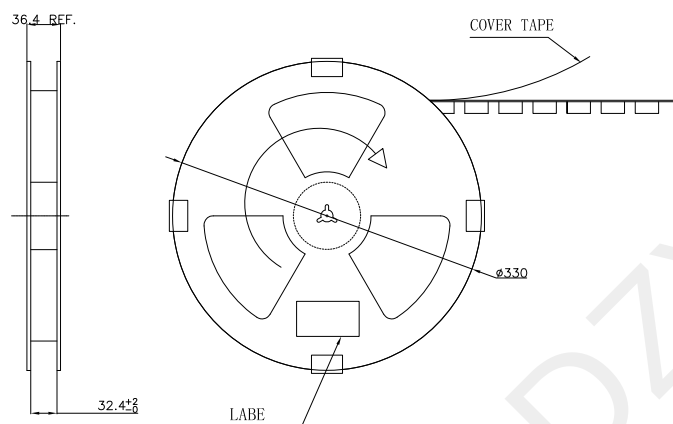
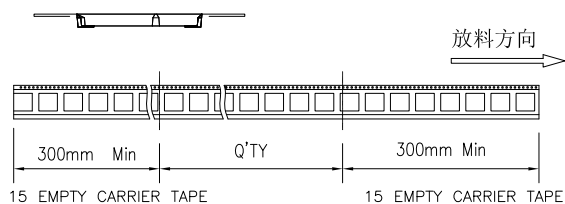
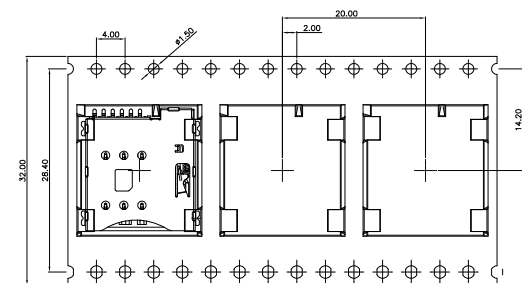
4) MECHANICAL CHARACTERISTICS

MATING CYCLE : 3000 CYCLES
Contact retention force: 50gf/pin Min.



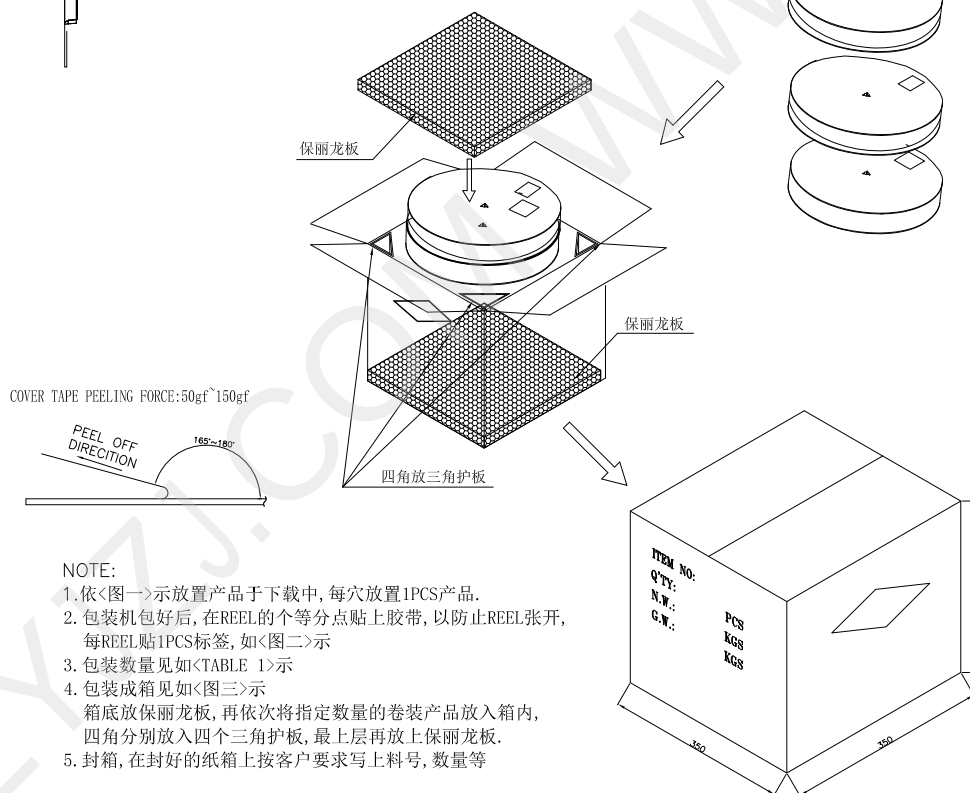
深圳市华宇创精密电子有限公司

TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X' $\pm 2'$ X.X' $\pm 0.5'$	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: MICRO SIM PUSH 6P 1.35H
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC326-SIM06-135
UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2210221329
			SHEET NO. 1 OF 1



<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
1200	9	10800



NOTE:

1. 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
2. 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
3. 包装数量见如<TABLE 1>示
4. 包装成箱见如<图三>示
箱底放保丽龙板, 再依次将指定数量的卷装产品放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
5. 封箱, 在封好的纸箱上按客户要求写上料号、数量等



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5'				包装图	
 UNIT: mm [inch]		CHECKED BY:	DATE :	PART NO.	
		马跃	2014-02-23	MOLD NO.	
		APPROVED BY:	DATE :	DRAW NO:	
		邱敏	2014-02-23	SHEET NO.	1 OF 1